

NOTE A: Pin numbering is for reference only to the function table. The pin numbering in this figure does not correspond to the numbering on the custom tape.

description

The MPT57216 is a 192-channel color thin-film transistor (TFT) LCD driver based on an active matrix LCD (AMLCD). It has 3 bits for each RGB input. These 3 bits are decoded internally to select one of eight bias-voltage levels, V0 to V7 for output, in order to support 512 colors ($R = 2^3 = 8$; $G = 2^3 = 8$; $B = 2^3 = 8$; $RGB = 2^9 = 512$).



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functional block diagram



NOTE A: These terminals are for factory testing only and should be left open.



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power supply circuit



NOTE A: Separation between high voltage GND line and logic GND line is recommended to avoid noise problems.



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decoding for OUT0 – OUT191



NOTE A. The C32 – C10 inputs are decoded internally to derive SEL0 – SEL7 from the output of a 3-to-8 decoder. Only one of the decoder outputs, SEL0 – SEL7, puts ≈V_{EE} on the P-CH and ≈V_{SS} on the N-CH of its corresponding transmission gate. This allows only one of eight bias voltages, V0 – V7, to pass onto OUTn.



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Terminal Functions

NAME	TERMINAL	I/O					FUNCT	ION									
C32 C31	207 208	8 9							t each of 3 RGB nber and n = weig	ports selects up to 8-l ght selected.	ev-						
C30 C22	209 210			INPUT OUTPUT			UT										
C21 211 C20 212 C12 213 C11 214				C32 C22 C12	C31 C21 C11	C30 C20 C10	DSEL = (Noninver		DESEL = H (Inverted)								
C10	214 215			1 1 1 0 0 0	1 1 0 1 1 0	1 0 1 0 1 0 1	V7 V6 V5 V4 V3 V2 V1		V0 V1 V2 V3 V4 V5 V6								
				0	0	0	VO		V0 V7]							
CL	217	1								gister, data memory, a or normal operation.	and						
CLK	216	I	stored in	Clock input. CLK is the rising edge systems clock for the 64-bit shift register. Also, 9 bits of data are stored in the data memory by the falling edge of CLK. The clock control circuit stops the internal system clock to save power consumption after 64 clocks.													
DSEL	205	205 I	Data sele	ect input. T	his input	inverts the	data on C10 t	to C32	input.								
					INPUT D	DATA	DAT	A MEMORY									
										C10 to	C32 [DSEL = L	DSEL =	н			
				0		0	1										
				1		1	0		l								
EIO1	219	I/O	Enable I/	O. EIO1 a	nd EIO2 a	are data en	able input/out	put for	cascade interface	Э.							
EIO2	204				R/L		EIO1		EIO2								
										H (Left S	hift)	Casc	ade Input	Casca	ade Output (OUT	0 – OUT191)	
				L (Right S	Shift)	Casc	ade Output	Casca	ade Input (OUT19	91 – OUT0)							
LS	218	I	192) and	Latch Strobe Input. When LS is high, 9 x 64 bits of data memory is latched into the display latch (3 x 192) and passed through a 3-to-8 decoder. The decoder selects one of eight bias voltage $V0 - V7$ to be passed on to OUTn using a transmission gate. LS also clears the shift register and clock control circuit.													
MODE	231	1	Mode inp connecte	Mode input. MODE is used for factory testing only and should be left open. The internal pullup resistors connected to V _{DD} force the inputs into a high state.													
OUT0 – OUT191	1 – 192	0					display. C1x, where n = 0 -			s voltages, V0 – V7, o	on						



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Terminal Functions (continued)

NAME	TERMINAL	I/O			FUI	NCTION					
R/L	221	I	shift regis three diff three at a	elect right/left shift. \overline{R}/L selects which direction the EIOn enable pulse advances through the 64-bit ift register. It also selects which direction the 3-bit \times 3 RGB data from the data latch is loaded into ree different but adjacent channels of data memory. This data is loaded as the channels are enabled ree at a time by the enable pulse from the shift register. It advances from one output to the next when ifting through the shift register with each clock pulse.							
				R/L H L							
				Shift Direction	Left	Right					
				EIO1	Input	Output					
				EIO2	Output	Input					
				CLK	1, 2, 3, 64	1, 2, 3, 64					
				C32 – C30	2, 5, 8, 191	191, 188, 185, 2					
				C22 – C20	1, 4, 7, 190	190, 187, 184, 1					
				C12 – C10	0, 3, 6, 189	189, 186, 183, 0	ļ				
TEST1 TEST2	193 194	I			ST2 are used for factor to V _{DD} force the input	y testing only and should be s into a high state.	left open. The internal				
V0 – V7 V0 – V7	202 – 195 223 – 230	I	device ou the V0 to	Eight-level input bias voltage for output buffer. After the three bits for each RGB color are decoded, the evice outputs one voltage level from the eight possible bias voltages ($V0 - V7$). There is no priority on the V0 to V7 terminals. A pair of V0 to V7 bias voltage terminals are provided. Each pair of terminals is equired to be connected together externally.							
V _{DD}	206		5-V supp	ly input for logic o	circuits						
VEE	222		Supply in	Supply input for level shifter and output transmission gate.							
V _{SS1} V _{SS2}	220 203		Ground t	Ground terminals							



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absolute maximum ratings over operating free-air temperature range[†]

Supply voltage range, V _{DD} (see Note 1)
Input voltage range, V _I (CLK, LS, R/L, CL, C32 to C10, DSEL, EIO1, EIO2)0.3 V to V _{DD} + 0.3 V
Output voltage range, V _O (E101, E102) -0.3 V to V _{DD} + 0.3 V
Output bias voltage range for LCD, Vx -0.6 V to V _{DD} + 0.6 V
Input current, I ₁ ± 10 mA
Output current, I _{O:} E101, E102
OUT0 to OUT191 5 mA
Power dissipation, P _D 0.3 W
Operating free-air temperature range, T _A
Storage temperature range, T _{stg}

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: Voltage values are with respect to V_{SS1} and V_{SS2}

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}	See Note 2	4.5	5	5.5	V
Supply voltage, VEE	See Note 2	14		18	V
Output bias voltage for LCD driver	V0, V1, V2, V3, V4, V5, V6, V7 See Note 2	0		V_{EE}	V
High-level input voltage, VIH	CLK, LS, DSEL, R/L, CL, EIO1, EIO2, C32 to C10	0.8 V _{DD}		V _{DD}	V
Low-level input voltage, VIL	CLK, LS, DSEL, R/L, CL, EIO1, EIO2, C32 to C10	VSS		0.2 V _{DD}	V
Clock frequency at CLK, f(CLK)	CLK			15	MHZ
Clock frequency at LS, f(LS)	LS			100	kHz
Operating free-air temperature, T _A		-55		125	°C

NOTE 2: Turn-on and -off sequence of power must be as follows: Turn-on sequence: $V_{DD} \rightarrow Logic Input \rightarrow V_{EE} \rightarrow V7$ to V0 Turn-off sequence: V7 to V0 $\rightarrow V_{EE} \rightarrow Input \rightarrow V_{DD}$



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	PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
VOH	High-level output voltage	E101, E102	I _{OH} = -0.3 mA	V _{DD} -0.4		V
VOL	Low-level output voltage	E101, E102	I _{OH} = 0.3 mA		0.4	V
Ι _{ΙΗ}	High-level input current	<u>C</u> LK <u>, D</u> SEL, LS, R/L, CL, EIO1, EIO2, C32 to C10	$V_{IH} = V_{DD}$		10	μΑ
Ι _{ΙL}	Low-level input current	<u>C</u> LK <u>, D</u> SEL, LS, R/L, CL, EIO1, EIO2, C32 to C10	V _{IL} = V _{SS}		10	μΑ
l _{lkg}	Input leakage current	V7 to V0	V _{SS} < Vx < V _{EE}	-100	100	μA
ΔVIO	Voltage difference between Vx to OUTn (voltage variance)	Vx - OUTn	$I_{I/O} = \pm 10 \ \mu A$, $V_{SS} < Vx < V_{EE}$		50	mV
R _{o(on)}	Output resistance	OUT0 – OUT191	$I_{O} = \pm 100 \ \mu A$		5	kΩ
I _{DD}	Supply current	V _{DD}	$ \begin{array}{ll} f_{(CLK)} = 15 \mbox{ MHZ}, & f_{(ElOxin)} = 30 \mbox{ KHZ}, \\ f_{(LS)} = 30 \mbox{ KHZ}, & V_{DD} = 5.5 \mbox{ V}, \\ V_{EE} = 18 \mbox{ V} \end{array} $		4	mA
IEE	Supply current	V _{EE}	$ \begin{array}{ll} f_{(CLK)} = 15 \mbox{ MHZ}, & f_{(ElOxin)} = 30 \mbox{ KHZ}, \\ f_{(LS)} = 30 \mbox{ KHZ}, & V_{DD} = 5 \mbox{ V}, \\ V_{EE} = 17 \mbox{ V} \end{array} $		1	mA
h	Standby ourrent	V _{DD}	V _{DD} = 5 V, V _{EE} = 17 V See Note 3		300	μΑ
I(standby)	Standby current	V _{EE}	V _{DD} = 5 V, V _{EE} = 17 V See Note 3		100	μΑ

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

NOTE 3: Test conditions of standby current are added at $\overline{R}/L = V_{DD}$, and EIO1 = V_{SS}.

timing requirements, V_{DD} = 5 V, T_A = –55°C to 125°C

	PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
^t CLK	Clock cycle time		See Figures 2 and 4	66		ns
^t W(L)	Low-level pulse width	CLK	See Figure 2	23		ns
^t w(H)	High-level pulse width		See Figure 2	18		ns
t _{su}	Data setup time	Cxx – CLK	See Figure 4	10		ns
t _h	Data hold time	CLK – Cxx	See Figure 4	15		ns
^t w(EN)	Enable high-level pulse width	EIO1, EIO2	See Figure 2	1/fCLK		ns
^t su(EN)	Enable setup time	EIOx – CLK	See Figure 2	20	30 or 1/fCLK	ns
^t h(EN)	Enable hold time	CLK – ElOx	See Figure 2	10	^t CLK × 62	ns
^t w(LS)	Latch strobe high-level pulse width		See Figure 3	40		ns
t _{su(LS)}	LS setup time	LS	See Figure 3	66		ns
^t h(LS)	LS hold time		See Figure 2	40		ns
t _{su} (DSEL)	DSEL setup time	ElOx – DSEL	See Figure 2	66		ns



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switching characteristics, V_{DD} = 5 V, T_A = –55°C to 125°C over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT	
^t p(EN)	Enable propagation delay time	CLK – EIOx	C _L = 35 pF, See Note 4 and Figure 4		40	ns
^t p(OUT)	Output propagation delay time	LS – OUTn	C _L = 200 pF, See Note 4 and Figure 3		3.0	μs

NOTE 4: CL includes probe and jig capacitance.



PARAMETER MEASUREMENT INFORMATION

- NOTES: A. Input pulse generators have the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, t_f \leq 15 ns, t_f \leq 15 ns, z₀ = 50 Ω . B. V_{IH} and V_{IL} for all waveforms are at 0.8 V_{DD} and 0.2 V_{DD} respectively.
 - C. All timing parameters and measurements are referenced at the 0.5 V_{DD} point of each waveform.

Figure 2. EIOx (IN), LS, and DSEL Timing Waveforms



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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. Case of data input change: if data has changed after the last clock of 1H, then it is recommended to add a dummy clock of one pulse after the last 1H pulse of the clock.
 - B. Case of suspending clock (CLK) after data transfer (1H) completion: it is recommended that the data input not be changed while the clock is suspended.
 - C. All timing parameters and measurements are referenced at the 0.5 V_{DD} point of each waveform except t_{p(OUT)} on the OUTn waveform. The reference point on the OUTn waveform is V0+0.1 Vx for positive-going transitions and V0-0.1 Vx for negative-going transitions.
 - D. OUTn waveform transitions are from V0 level to Vx level. Maximum V0 and Vx levels are 8.0 V due to tester limitations.
 - E. Input pulse generators have the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, t_f \leq 15 ns, t_f \leq 15 ns, z_O = 50 Ω .
 - F. VIH and VIL for all waveforms are at 0.8 VDD and 0.2 VDD respectively.

Figure 3. LS and OUTn Timing Waveforms



NOTES: A. Input pulse generators have the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, t_f \leq 15 ns, t_f \leq 15 ns, z₀ = 50 Ω . B. V_{IH} and V_{IL} for all waveforms are at 0.8 V_{DD} and 0.2 V_{DD} respectively.

C. All timing parameters and measurements are referenced at the 0.5 V_{DD} point of each waveform.

Figure 4. Cxx and EIOx (OUT) Timing Waveforms



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